The Valley Megaphone

Newsletter of the
Institute of Electrical and
Electronics Engineers, Inc.,
Phoenix Section
December 2014,
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Executive Committee 2014

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In this Issue of the Valley Megaphone: Table of Contents

(Please Click on the heading below to go directly to that page)

IEEE Phoenix Section on-line updates can be found at http://sites.ieee.org/phoenix/ and on LinkedIn at:http://www.linkedin.com/groups?gid=2765918 and on Facebook at: https://www.facebook.com/IEEEPhoenixSection

Please send announcements for the *Valley Megaphone* to Mahesh Shah at mkshah@ieee.org for inclusion in the Section Calendar.

All meetings announced in the Phoenix Section Megaphone or on the Phoenix Section Calendar are open to everyone (IEEE members and non-Members)

Chapters

Signal Processing & Communications
Pavan Turaga
pturaga@asu.edu

Computer Society
Jerry Crow
jerry.crow@computer.org

CPMT Society
Mahesh Shah
480-544-9438
mkshah@ieee.org

Education Chapter
Martin Reisslein, 480-965-8593
reisslein@asu.edu

EMBS Chapter
TBD

EMC Society
Brett Gassaway, 480-926-3100
brettg@compliancetesting.com

Power & Energy Society
Craig Smith
craig.smith@aps.com

Solid State Circuits
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Mirembe@ieee.org

Teacher-In-Service
Rickie Currens
Rickie.Currens@att.net

Waves & Devices Society
Steve Rockwell
steve.rockwell@ieee.org

Life Members
Les Daviet II
lesdavietii@cs.com

Women In Engineering
Shamala Chickamenahalli
shamala.chickamenahalli@intel.com

Young Professionals
Shafiul "Jacky" Islam 520-245-9010
shafiul.islam@intel.com

The Valley Megaphone is the newsletter of the Phoenix Section of the Institute of Electrical and Electronics Engineers. It is published monthly and reaches about 4000 members. Submit articles, advertisements, and announcements to Surinder Tuli at the above email address. Deadline for announcements and advertisements is the third Friday of the month prior to publication. Advertising Rates: Full page: $200, 3/4page: $125, ½ page: $75, 1/3 page: $50, 1/4 page: $25. Change of address/email? Call toll free 1-800-678-IEEE. Please allow 6-8 weeks. Section Web Page is http://sites.ieee.org/phoenix/

U – News

(for Student Members)

Updates of Student Advisors and Committee Members

Each Student Branch noted on the right side of this page should review current information on Advisors and Student Committee Members and forward to my attention within this week, as we are reviewing contacts for reporting and activities including Student Monthly Meetings.

S. Diane Smith
602-749-4601
sdianesmith@computer.org
Student Activities Chair

Student Branches

ASU Main, Engineering
Chair: Nick Spirakus
480-789-9867,
nmspirak@asu.edu
Advisor: Cihan Tepedelenlioglu,
480-965-6623, **cihan@asu.edu**

ASU Main, Computer Society
Chair: TBD
Advisor: Guoliang Xue
480-965-6218, **xue@asu.edu**

ASU Polytechnic
Chair: TBD
Advisor: TBD

DeVry, Phoenix
Chair: Lori Renaldi
lorirenaldi@computer.org
Advisor: Diane Smith
dsmith2@devry.edu

DeVry, Computer Society
Chair: TBD
Advisor: Diane Smith
dsmith2@devry.edu

NAU, Engineering
Chair: TBD
Advisor: Niranjan Venkatraman
v.niranjan@ieee.org

Embry-Riddle, Prescott
Chair: Lisa M. Ferguson
FERGUSL2@my.erau.edu
Advisor: John E. Post
postj@erau.edu

U – Newsbytes

ASU Polytechnic is currently seeking Advisor for the Student Branch. Please email Diane (at email address above) with Recommendations.

The Department of Computer, Electrical, and Software Engineering at **Embry-Riddle Aeronautical University** in Prescott, AZ invites applications for a faculty position (tenure-track or tenured) at the assistant or associate professor level. The successful candidate should have a BS degree in Electrical or Computer Engineering, and either an earned doctorate in Electrical or Computer Engineering, or a MS degree in Electrical or Computer Engineering, or equivalent, and extensive industrial experience with wireless or wireline communications, analog or power electronics, navigation systems, or avionics systems. Preferred areas of expertise for this position include extensive knowledge of electronic and wireless (both analog and digital) communications systems theory and practice as well as the ability to develop and manage senior design projects in this area. Significant industrial, entrepreneurial and/or teaching experience would strengthen a candidate's credentials, but recent graduates are encouraged to apply.

Apply online at www.erau.edu/jobs and search for positions at Prescott.
Contact Professor Cone at conec@erau.edu for further information.

Upcoming Conferences in Region 6

Hello IEEE Student Members!

IEEE Region 6 is putting on the first **Rising Stars Conference for Young Engineers**. If you are a young professional or IEEE student member or know someone who is we would like you to invite them to register for this premiere student and young professional conference. The 2015 Rising Stars Conference will bring together the most promising young engineers in the region to connect, be inspired, develop themselves and get exposure to top tech companies from around the world. Young engineers can find out about the event and register at: http://sites.ieee.org/risingstars/.

Taking place January 2nd-4th, 2015 at the Riviera Hotel in Las Vegas, Nevada, this conference is held immediately prior to two other shows; the Storage Visions Conference as well as the Consumer Electronics Show.

The program consists of various themes, including but not limited to Professional Development, Visualization (think: animation, image processing and hi-tech engineering applications), Entrepreneurship, Mentoring and the Internet of Things. We also plan to have development kit sessions as well as a backstage engineering tour of a Cirque du Soleil show!

Don't miss this opportunity to reach out to your fellow young engineers, engage industry and learn under one desert roof. There are limited spots for elements of the program - so register now! Please note that separate registration is required for the Storage Visions Conference and registration for the Storage Visions Conference provides an exhibit pass to the Consumer Electronics Show.

With only a few months to go - we look forward to hearing from and hosting you in Las Vegas.

Best regards,
2015 Rising Stars Organizing Committee

2015 IEEE/MTT-S International Microwave Symposium - MTT 2015 Will be held May 16 to 22 2015

2015 International Conference on Microelectronic Test Structures (ICMTS) will be held March 23 to 26 2015

2015 85th ARFTG Microwave Measurement Conference (ARFTG) will be held on May 22, 2015

2015 IEEE International Conference on Cloud Engineering (IC2E) will be held March 9 to 13

2015 IEEE Workshop on Automatic Speech Recognition and Understanding (ASRU) will be held Dec 13 to 16, 2015

Metro Area Workshop

We are trying to plan an all day workshop here in Phoenix for the spring of 2015. It will be for learning and networking and will be kept affordable so that everyone who wants to attend can. We are planning on having a keynote speaker and then break into a number of classes all day, with breaks for snacks, lunch, and networking.

Anyone who would like to volunteer to help or is able to teach a class, please contact me at Phoenix.conferences@ieee.org or bradscientist@ieee.org

We are also planning on having exhibits for the attendees to learn about new companies, products, and to meet other people. The booths will be reasonably priced, and if anyone is interested, please contact me at the email listed in the lines above.

Call for Papers
28th International Conference on Microelectronic Test Structures

March 23-26, 2015, Phoenix, Arizona USA

General Chair:
Larg Weiland
PDF Solutions
larg.weiland@pdf.com

Technical Chair:
Colin McAndrew
Freescale Semiconductor, Inc.
Colin.McAndrew@freescale.com

Tutorial Chair:
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European Representative:
Anthony Walton
Scottish Microelectronic Centre
University of Edinburgh
Anthony.Walton@ee.ed.ac.uk

USA Representative:
Loren Linholm
linhlw@comcast.net

Conference Manager:
Wendy Walker
Widerkehr and Associates
wwalker@widerkehr.com

The 28th International Conference on Microelectronic Test Structures (ICMTS) will be held in Phoenix, Arizona, USA, bringing together designers and users of test structures to discuss recent developments and future directions. The conference will be held March 24-26, 2015, preceded by a one-day Tutorial Short Course on Microelectronic Test Structures on March 23. There will be an equipment exhibition relating to test structures and measurements. Original papers are solicited presenting new developments in test structures, as well as their implementation, measurement, and application, related to semiconductors, nanotechnology, and MEMS. A Best Paper award will be presented by the Technical Program Committee. The conference is sponsored by the IEEE Electron Devices Society and all published papers will be posted to IEEE Xplore®.

Topics of relevance to ICMTS include, but are not limited to:

Material and Process Characterization: Wafer material evaluation for SiGe, strained Si, Si-on-insulator, Ge, GaAs, GaN and other compounds. Resistivity, mobility, stress, contact resistance, dielectric, and interconnect measurements. Test structures and methods to evaluate new materials and devices, e.g. graphene and CNTs.
Test structure design methods: Flows for automated test structure design, generation, and verification; design-for-analysis, parameterized design, layout issues (grid, hierarchy, misalignment), switched arrays.
Replicated Feature Metrology: Level-to-level registration, overlay, CD uniformity and control, non-electrical characterization techniques, mask and reticle process control.
Manufacturing of Integrated Circuits and MEMS: Evaluation of individual and groups of integrated circuit, device, and MEMS process steps and elements: transistors, diodes, mechanical structures, device isolation, memory cells, and interconnect. Assessment of MMICs and RF components and products. Evaluation and optimization of standard cell macros and other circuits.
Reliability and Product Failure Analysis: Test structures for quality assurance, transistor, thin film, dielectric, and interconnect reliability, thermal monitoring and analysis, accelerated wafer level tests, wafer level burn-in, failure identification, reliability prediction.
Nanotechnology, Displays, and Emerging Devices: Test structures and methods to evaluate nanotechnology (materials and devices), displays, optoelectronic materials and devices, novel memories, and related materials.
(BIO-)MEMS, (BIO-)Sensors, and Actuators: Test structures for MEMS and micromachining including physical/chemical/optical/bio sensors, photonic devices, amorphous silicon films and devices.
Device and Circuit Modeling, Parameter Extraction: Model parameter extraction, RF device modeling, de-embedding, pulsed measurements, DC and high frequency measurement techniques and applications.
Technology R&D, Integration, and DFM: Test structures for FEOL or BEOL evaluation, design rule determination, process uniformity and worst-case analysis, test structures to assess integration and new technologies, switched array test chips/devices for large scale evaluations and reduced pad count.
Test Circuits: Novel on-wafer circuits for characterization of manufacturing technologies, variability, yield, and performance. Circuits to simplify probing, improve measurement robustness, and reduce pad count.
Yield Enhancement, and Production Process Control: Yield enhancement structures and methods, critical area calculation, defect estimation structures and methods, yield modeling, evaluation of design-manufacturing interactions, place and route methodology, and statistical process control. Large-scale, many-component test arrays and multiplexing techniques for technology assessment.
Test Structure Measurement Utilization Strategy: Test equipment, probing and programmable testing for process diagnostics, optimizing test throughput, database and data analysis methods, statistical data analysis, expert systems and related techniques, including capacitance, voltage, current, resistance, optical, and thermal measurements.
Matching and Variability Test Structures: Matching and variability of components (transistors, resistors, capacitors, inductors) and layout for circuit applications and their evaluation. Characterization of identically designed components. Modeling of matching and variability.

Authors are asked to submit an abstract of up to four pages in PDF format (font-embedded). The first page **must** consist of a title, a 50-words summary, author name(s), the full address, fax number, and e-mail address of the lead author, and author preference for oral or poster session presentation, if any. The body of the abstract should be three pages or less consisting of one page of text (800 to 1000 words) and up to two pages containing major figures and tables. Please visit the ICMTS 2015 official web site icmts2015.pdf.com for further information and paper submission. You may care to join the ICMTS group at www.linkedin.com.

The selection process will be based on the technical merit and will be highly weighted in favor of papers that have a high test structure content, include measured data and analysis, together with illustrations of the test structures involved. The submission deadline is **October 17, 2014**. Notice of paper acceptance, with instructions for manuscript preparation for the conference proceedings, will be sent to the authors of the papers selected for presentation by early December, 2014. The deadline for submission of the final paper will be January 20, 2015.

Details of the venue, hotel, registration, etc. will be posted at icmts2015.pdf.com as they are finalized.

For further technical information, please contact the technical chair:
Colin McAndrew, Freescale Semiconductor, Inc., Colin.McAndrew@freescale.com

International Microwave Symposium
IEEE 17 – 22 May 2015 Phoenix, AZ MTT-S

IMS

Come join us in Phoenix and enjoy the flagship Microwave Theory and Techniques Society (MTT-S) Conference

The IEEE Microwave Theory and Techniques Society's 2015 International Microwave Symposium (IMS2015) will be held **17 - 22 May 2015** at the Convention Center in Phoenix, Arizona as the centerpiece of Microwave Week 2015. IMS2015 offers technical sessions, interactive forums, plenary and panel sessions, workshops, short courses, industrial exhibits, application seminars, historical exhibits, and a wide variety of other technical and social activities including a guest program. As usual, the Microwave Week 2015 technical program also comprises the RFIC symposium (www.rfic2015.org) and the ARFTG conference (www.arftg.org). Unique to Microwave Week in 2015, a High School Science and Engineering Invitational will be held.

With over 9,000 participants and 800 industrial exhibits of state-of-the-art microwave products, Microwave Week is the world's largest gathering of Radio Frequency (RF) and microwave professionals and the most important forum for the latest research advances in the field.

Call for Papers
Authors are invited to submit technical papers describing original work on Radio-Frequency, microwave, millimeter-wave, and terahertz (THz) theory and techniques. The deadline for submission is **8 December 2014.** Please refer to the IMS2015 website (www.ims2015.org) for detailed instructions concerning paper submission. **Please don't wait** until the last day to start using the paper submission process. Those unfamiliar with the process may encounter paper formatting or clearance issues that may take time to resolve. The Symposium proceedings will be recorded on electronic media and archived in IEEE-Xplore. Authors of accepted papers should consider submitting an extended version of their symposium paper for possible publication in the *IEEE Transactions on Microwave Theory and Techniques.*

Emerging technical areas:
IMS2015 enthusiastically invites submission of papers that report state-of-the-art progress in technical areas that are outside the scope of those specifically listed in this Call for Papers, or that may be new to the symposium, but are of interest to our attendees.

Student paper and student design competitions:
Eligible students are encouraged to submit papers for the student paper competitions. In addition, eligible students or student teams are invited to consider taking part in student design competitions during the IMS2015, which are organized and sponsored by various Technical Committees (TC) of the MTT-S Technical Coordination Committee (TCC). Please visit the IMS2015 web site for full details.

MicroApps:
The Microwave Application Seminars serve as a forum for exhibitors at the IMS to present the technology behind their commercial products and their special capabilities. The presentations are open to all conference and exhibit attendees. All submissions must be made through email to microapps@ims2015.org. Please refer to the IMS2015 website for more information on submitting MicroApps technical papers.

We are looking forward to meeting you in Phoenix and sharing some of the hottest new microwave ideas under the sun!

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

2014 Executive Committee for CPMT Chapter for IEEE-Phoenix Section

Position	Name	Phone Contact	Email Contact
Chair	Dr. Mahesh K. Shah	(480) 544-9438	mkshah@ieee.org
Asst. Chair	Mr. Vivek Gupta	(480) 734-2366	vmgupta@msn.com
Secretary	Dr. Devarajan Balaraman	(480) 619-0944	iamgoinbiking@gmail.com
Treasurer	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Program Chair	Mr. David Dougherty	(480) 245-8099	david.dougherty@freescale.com
Tutorial Chair	Dr. Ashish Gupta	(480) 554-2409	ashish.x.gupta@intel.com
Asst. Tutorial Chair	Adel Elsherbini	(734) 686-2278	a.elsherbini@gmail.com
Workshop Chair & Publicity	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Website Co-Chair	Huiyang Fei		Huiyang.H.Fei@ieee.org
Website Co-Chair	Bharat Penmecha	(480) 552 2511	bharat.penmecha@ieee.org

Tentative Schedule for Monthly Seminars

We are working to arrange monthly Seminars on topics of interest to our members. If you have suggestion for topics and/or speakers please contact any of the executive committee members listed above.

December 10 – Polymer Innovation for Mobile Packaging Application, John Hunt, ASE (US) , Inc

Additional Activities –Tutorial and Workshop

Phoenix section is planning to hold a Half Day tutorial on the topic of **Reliability Engineering** in 2015. In addition we are working with other Society Chapters to hold a workshop on **Emerging Device and Packaging Technology** also in 2015. Please wait for announcements in near future.

2015 Executive Committee

Announcement for 2015 Executive Committee positions was sent out via IEEE eNotice email to all CPMT Chapter members on record first on Nov. 25th, and Dec. 1st, 2014. Deadline for receiving the nominations is December 10, 2014. If you are IEEE & CPMT member and are willing to serve please contact the Nomination Committee Members: Dr. Vasudeva Atluri (Chair): vpatluri@ieee.org or Dr. Chuck Weitzel: c.weitzel@ieee.org

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

Wednesday, December 10th, 2014 at 5:30 PM

Polymer Innovation for Mobile Packaging Applications

John Hunt
ASE (US) Inc
7855 South River Parkway. Suite 212.
Tempe, AZ 85284 USA
john.hunt@aseus.com

ABSTRACT

Portable electronics have become ubiquitous tools for everyday living, from simple communication devices to complex social networking tools. Consumers expect ever more functionality with every generation of product, be it a cell phone, tablet or gaming device. With the consumer’s relentless quest for more features, faster processing, more memory, smaller size, and lower cost in their portable devices, the industry is turning to new foundry and packaging technologies to meet their goals. As we have tried to maintain the pace of Moore’s law, the introduction of advanced technology nodes has placed new challenges on the structures, materials, and processes used for packaging.

The drive for size reduction in portable devices has also resulted in smaller and more compact device and package structures, often with increased complexity. Paradigm shifts in technology have also introduced new packaging requirements. As an example, the rapid evolution of sensors and actuators into MEMS technology has rapidly expanded their use into portable devices. This has often introduced the need for new material and process complexities as each MEMS application has generated its own particular packaging requirements.

As we go forward, newer evolutionary and revolutionary technologies that are currently under development will find their way into these mobile devices. These are often variations of standard packaging, including Copper Pillar Flipchip, Fanout wafer level packaging, and variations of embedding technology using Substrate and Printed Circuit Board technologies.

Polymers play an instrumental role in these innovations as both processing consumables, and as structural materials that remain in the end products. Many of these advanced packages are still in the evolutionary development phase, and a large part of this evolution is the development and identification of polymers and other materials that will provide the most robust manufacturing processes, as well as the lowest cost and most reliable final package products. Many of these new materials will be evolutionary developments of existing products, but there will also be the need for new materials that have no current counterpart. This presentation will review the role of polymers used in packaging and for new and advanced polymeric structures. The performance requirements for the new material sets and for manufacturing processing will be discussed.

BIOGRAPHY

John Hunt is Director of Engineering, Product Promotion, at ASE (US) Inc., and provides technical support for the Introduction, Engineering, Marketing, and Business Development activities for Advanced Wafer Level Packaging Technologies at ASE. Prior to joining ASE, John was Technology Development Manager at AD Flex Solutions, a Flex circuit manufacturing and assembly company; and was Research and Development Engineering Manager at both Nortel and Digital Equipment Corporations. John has 40 years of experience in various areas of manufacturing, assembly and testing of electronics components and systems, with emphasis on the development of new technologies and processes. John holds a Bachelor’s degree from Rutgers University, and a Master’s Degree from the University of Central Florida.

Date: Wednesday, December 10th, 2014

Location: Group Conference Room, Freescale Semiconductor, Inc., Discovery Business Center, 2100 E. Elliot Rd. Tempe, AZ. Enter the facility through the Main (South) Lobby in building 94 and sign in with Security (*Photo ID required*) **BEFORE 6:00 PM**. You will be escorted to the meeting room. The presentation promptly starts at **6:00 PM**.

Agenda: 5:30–6:00 PM: Social/Refreshments, 6:00–7:00 PM: Presentation, 7:00 PM: Dinner
(Pizza and Soda will be provided by the IEEE Phoenix Section CPMT Society Chapter)

IEEE members and non-members are all welcome to attend.
Please arrive at the facility entrance no later than 5:45 PM.

For more information, please contact any of the following CPMT officers:

Vasu Atluri	(480) 227-8411	Devrajan Balaraman	(480) 619-0944	David Dougherty	(480) 413-6923
Adel Elsherbini	(734) 686-2278	Ashish Gupta	(480) 554-2409	Vivek Gupta	(480) 734-0266
Mahesh Shah	(480) 544-9438	Huiyang Fei		Bharat Penmecha	(480) 552-2511

SP-COM Phoenix Chapter

Please join our Google Group!

We have recently started a google group to be able to send you more timely announcements via email for upcoming events and talks. Please sign up for timely email announcements at the below link

https://groups.google.com/d/forum/ieee-sp-com-phoenix-chapter

We are limiting member permissions only to receiving emails posted by the group owner - the SP-COM chapter chair.

Technical Co-Sponsorship by the IEEE Signal Processing and Communications Chapter, Phoenix Section

We continue to post meeting notices on IEEE vtools at (https://meetings.vtools.ieee.org/main)

Upcoming Talks

(Please look for detailed announcement on our Google Group)

Akihiko (Ken) Sugiyama, IEEE Distinguished Lecturer

IEEE Fellow, Research Fellow of Information & Media Labs at NEC, Dec. 3rd, 2014.

Hamid Krim, IEEE Distinguished Lecturer

IEEE Fellow, Professor, North Carolina State University, on Feb 6th 2015.
Title: “Shape Analysis and Modeling in Video Applications: Activity Analysis”

Phoenix Chapter of the IEEE Computer Society

December, 2014

News

- We are actively hunting for a new meeting venue. Our November meeting at DeVry was the last meeting at that location. If anyone reading this has a suggestion for a venue for our meetings, please contact one of the officers. We need a room which will accommodate about 50 people, is available from 6:00 pm to 9:00 pm, has projection facilities, and is, hopefully, free. We are a 501(c)(3) organization.

- Officer elections for 2015 were held at the November. By consensus, the current officers were elected to serve in their current positions for 2015.

- The November presentation by Hal Berghel was excellent. He talked about the details of digital money laundering.

- We have several possible speakers identified for 2015. The tentative 2015 meeting dates are
    - January 7th
    - March 4th
    - May 6th
    - July 1st
    - September 2nd
    - November 4th

All dates are Wednesday. Meetings will be held from 6:00 pm to 9:00 pm. We will publish the venue for these meetings as soon as it is known.

Visit the CS Chapter website for the latest information: http://ewh.ieee.org/r6/phoenix/compsociety/.
For brief announcements regarding upcoming events we are also on Twitter: @IEEECS_PHX

If you would like to suggest a topic or speaker for any of our future meetings, please contact one of the chapter officers:

Chair: Jerry Crow (jerry.crow@computer.org)
Vice-chair: Brad Morantz (bradscientist@ieee.org)
Secretary/Webmaster: Audrey Skidmore (askidmore@computer.org)
Treasurer: Diane Smith (sdianesmith@computer.org)

IEEE Reliability Society
Arizona Chapter

The Reliability Society has just formed an Arizona chapter! This is a joint venture between the Ft. Huachuca, Tucson, and Phoenix Sections with the first event taking place this December. Please contact Phoenix Section Chair Bruce Ladewig (bruceladewig@ieee.org) if you are interested in attending.

Phoenix Section Life Member Affinity Group

Technical, Elections, & Administrative
Meeting December 9, 2014

Program Presentation: TBD

Meeting Agenda:
Attendee introductions
Program Presentation
Continued discussion of LMAG program for student assistance and possible scholarship program for HS students. Discuss results of visit to ASL by members.
Determine meeting dates for 2015.
Accept officer nominations and hold election of officers for 2015.
Administration Meeting.

Where: SRP's **PERA Club** Bighorn Room,
1 East Continental Drive, Tempe, AZ
Continental is West of 68th St., ½ mile south of McDowell Road
Enter the Private PERA Club and follow drive to large parking lot. Big Horn Room is the most South east building off parking.

When: Tuesday, December 9, 2014, 11:00am – 1:00pm, Registration fee is $15. This fee will include lunch provided by the PERA Club. Lunch will be: TBD

RSVP: Please advise Ronald Sprague if you plan to attend so accounting for lunch is possible.

Technical Presentations: The Program Chair is seeking suggestion from members for future presentations. Any ideas of interest to LM are open for consideration. Please contact Ronald Sprague Program Chair at r.sprague@ieee.org or any officer with ideas.

About IEEE Phoenix Section Life Member Affinity Group:

The IEEE Phoenix Section Life Member Affinity Group was organized to enable IEEE Life Members to retain active IEEE associations, contribute to the social good in their communities, advance IEEE's professional interests and enjoy each other's company.

Activities: Technical meetings scheduled in February, May, October, and December. Elections are held at the December meeting.

Future Technical Meetings: All meeting are scheduled at the SRP PERA CLUB. It is suggested you put these dates on your calendar to attend our meetings.

- Tuesday, December 9, 2014

Officers:

Chair	Leslie Daviet II	lesdavietii@cs.com
Vice Chair	Position is Vacant	
Secretary	Tom Lundquist	Tom.Lundquist@ieee.org
Treasurer	Leslie Daviet II	lesdavietii@cs.com
Program	Ronald L. Sprague,	r.sprague@ieee.org
Past Chair	A. Barry Cummings	abarrycummings@gmail.com

IEEE youngprofessionals

IEEE Young Professionals (formerly GOLD) Phoenix Section Executive Board

- Chairman: Shafiul "Jacky" Islam (shafiul.islam@intel.com)
- Vice Chair: Jennifer Taggart (jennifer.taggart@asu.edu)
- Secretary/Webmaster: Joseph Caglio (joseph.m.caglio@intel.com)
- Treasurer: Ashley Kelly (Meredith) (ashley.kelly@aps.com)

October 3, 2014, 1st Annual Career Mixer with IEEE Phoenix Young Professionals, Women in Engineering, and IEEE / IEEE-HKN ASU groups

IEEE Phoenix Young Professionals in alliance with Women in Engineering and IEEE/IEEE-HKN ASU groups organized first annual career mixer for fundraising, networking, and recruitment.
When: October 3, 2014 4:30-7:30pm Where: Old Main @ ASU, 400 East Tyler Mall, Tempe, AZ 85287
For more information (including organizing committee) please visit: https://meetings.vtools.ieee.org/m/28127
We had sponsorships from APS, Chrysler, Electron International Incorporated, Intel Corporation, Kimley-Horn, and Texas Instruments. This event was very successful where we had about 180 attendees and many students were recruited. This was one of the largest event as part of IEEE GOLD (now Young Professionals) Strategic Alliance proposed by Shafiul "Jacky" Islam at Southwest Area Meeting on August 24, 2013 in Phoenix, Arizona. We look forward to continue as a strategic alliance to hold our upcoming events.

October 28, 2014, ASU Fulton Engineering Career Exploration Night for Freshman

Lesley Polka represented IEEE Young Professionals, and (along w/ Shamala) Women in Engineering and Phoenix Section at the event.

November 7, 2014, FE and PE Exams for IEEE Phoenix Young Professionals Affinity Group

IEEE Phoenix Young Professionals in alliance with Women in Engineering, and IEEE / IEEE-HKN ASU is organizing this technical talk / lecture by Barbara J. McMinn, P.E. (refreshments will be provided at the event).
When: November 7, 2014 6:00pm Where: GWC 487, 650 E. Tyler Mall, Tempe, AZ 85281
This presentation will provide basic information related to (FE and PE) application process and preparation strategies, and will, hopefully, enable the participants to develop preparation strategies that align with their needs. Ms. McMinn is a Consulting Engineer, Arizona Public Service Company (APS), and a 29 year member of the Institute of Electrical and Electronic Engineers (IEEE). She was the 2014 Chair of the IEEE Phoenix Section through July.

Registration: https://meetings.vtools.ieee.org/m/30005

Organizers: Shafiul "Jacky" Islam (shafiul.islam@intel.com)
Ashley Kelly (ashley.kelly@aps.com)

December 16, 2014, 1st Leadership Conference with IEEE Phoenix Young Professionals, Women in Engineering, and IEEE / IEEE-HKN ASU groups -- Career Paths and Personal Journeys of Select Intel and IEEE Leaders

IEEE Phoenix Young Professionals in collaboration with Women in Engineering and IEEE/IEEE-Eta Kappa Nu ASU groups is organizing our first leadership conference as part of IEEE Young Professionals Strategic Alliance initiative.
Please join us to learn about career paths and personal journeys of select Intel and IEEE leaders that can offer lessons on achieving excellence in leadership. Further the conference will provide networking opportunities.
When: December 16, 2014 Where: Intel Chandler Campus, 5000 West Chandler Blvd, Chandler, Arizona 85226
For registration, speaker biographies, recent information (including organizing committee) please visit: https://meetings.vtools.ieee.org/m/20965

IEEE Phoenix Young Professionals Succession Plan and Notice of Election

According to the succession plan recommended by Shafiul "Jacky" Islam, Jennifer Taggart will be the Chair of IEEE Phoenix Young Professionals effective January 1, 2015. Jacky will continue to mentor officers as Past Chair effective January 1, 2015 and continue the spirit and momentum of IEEE Young Professionals Strategic Alliance.
Anyone interested to serve in Vice Chair, Secretary, or Treasurer position, please contact any of the executive board members. We will hold an election either in December 2014 or in January 2015.

2014 IEEE Phoenix Section News

Executive Committee Meeting

No meeting of Executive Committee in July & August

Normal meetings are on first Tuesday of the month from 6:00 PM to 8:00 PM
The Airport Hilton Phoenix,
2435 S 47th St. Phoenix, AZ 85034, (480) 894-1600.

2014 Executive Committee

Chair:	Bruce Ladewig
Vice Chair:	Bruce Ladewig
Secretary:	Surinder Tuli
Treasurer:	Vivek Gupta
Past Chair:	Charles Weitzel

Executive Committee Meetings

Date: First Tuesday of every month, except July and August
Time: 6:00 – 8:00 p.m.
Location: Hilton Phoenix Airport, 2435 South 47th Street, Phoenix, AZ 85034

IEEE Phoenix Section Annual Banquet 2014 Photos are Posted at:

http://sites.ieee.org/phoenix/2014/03/03/pictures-from-the-2014-annual-banquet/

IEEE Senior Member and Fellow Grade

IEEE Phoenix Section Membership Development would like to nominate eligible IEEE Members from the Section to Senior Member and Fellow Grades. Please review the requirements at www.ieee.org for eligibility.

Eligible candidates are requested to send in their resumes to Dr. Vasudeva P. Atluri, Membership Development Coordinator, at vpatluri@ieee.org and Dr. Charles E. Weitzel, Section Chair, at c.weitzel@ieee.org for consideration.

IEEE Phoenix Section Annual Banquet

Save the Date

IEEE Phoenix Section Annual Banquet 2015
Saturday, February 7, 2015
Grand Ball Room, Hilton Phoenix Airport

5:30 PM to 6:30 PM - Registration & Social Hour
6:30 PM to 7:30 PM – Dinner
7:30 PM to 8:00 PM – Welcome & Section Program
8:00 PM to 8:30 PM – Keynote Presentation "Grand Canyon and Its Wonders"
by Prof. Thomas Short, Director, Arizona State University
8:30 PM to 9:30 PM – Section Award Presentation

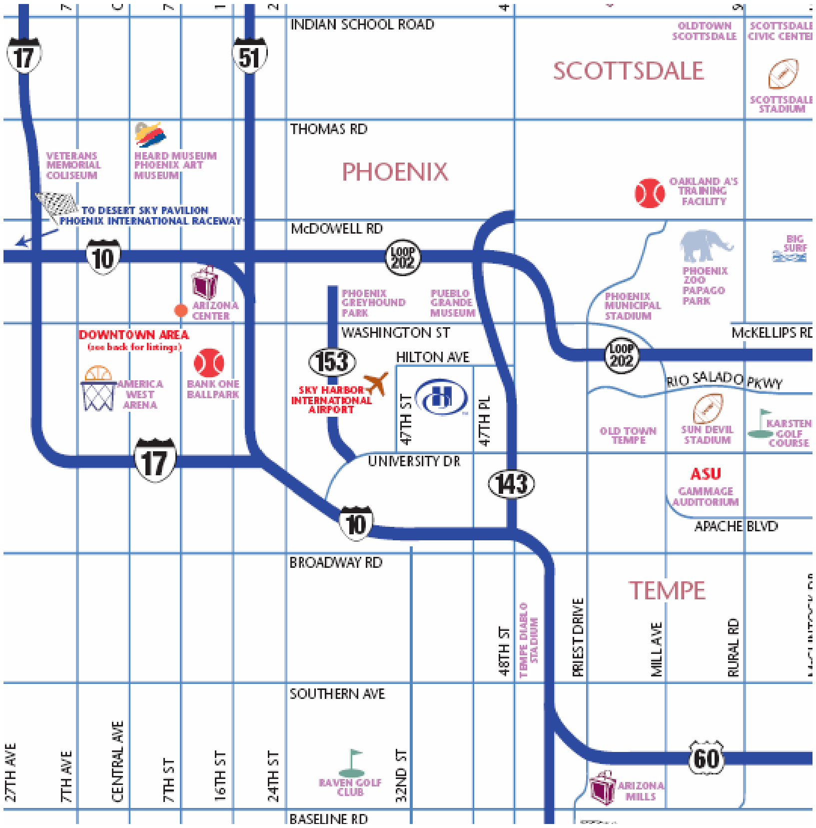
IEEE Phoenix Section
Annual Banquet 2015
Saturday, February 7, 2015

Venue

Hilton
Phoenix Airport

Hilton Phoenix Airport
2435 South 47th Street
Phoenix, Arizona 85034
(480) 894-1600

West of Hohokam (143) Freeway
and North of University Drive



IEEE Phoenix Section Awards

The IEEE Phoenix Section recognizes the contributions of members, non-members, society chapters, affinity groups, student branches, corporations, and educational institutions at the annual banquet. The next banquet is scheduled for Saturday, February 7th, 2015 at Hilton Phoenix Airport located at 2435 South 47th Street, Phoenix, AZ – 85034 from 5:30 PM to 9:30 PM (Tel: 480-894-1600).

The Section is pleased to issue a call for nominations for this year's Section awards. The scope and purpose of the Section Awards Program is to plan, promote and implement IEEE award programs that recognize outstanding performance in furthering the objectives and professional aims of the IEEE Phoenix Section, the IEEE, and the IEEE-USA, and to stimulate others to pursue such achievements of excellence.

The Phoenix Section has established the following general award categories:

- Member
- Society Chapter/Affinity Group
- Non-member
- Corporate
- Educational
- Section Chair

The Awards Guide lists the awards along with the selection criteria that will be implemented for selecting the award recipient. The Awards Guide can be accessed at http://sites.ieee.org/phoenix.

Please read through the Awards Guide to help you in selecting the award category for nomination.

All sections of the form should be completely filled electronically. Submission of additional documents such as resume in support of the nomination is highly encouraged.

Key dates:
Submission deadline: Sunday, January 4th, 2015
Awardees and nominators will be informed on: Sunday, January 11th, 2015

Only nomination forms submitted by the deadline will be reviewed by the awards committee consisting of the following IEEE Phoenix Section Officers:

- Awards Committee Chair: Dr. Vasudeva P. Atluri
- Past Chair: Dr. Charles E. Weitzel
- Chair (Interim) / Vice-Chair: Mr. Bruce J. Ladewig
- Secretary: Mr. Surinder K. Tuli
- Students Activities Coordinator: Dr. S. Diane Smith

If you have any additional questions, please contact Dr. Vasudeva P. Atluri, Section Awards Committee Chair, at (480) 227-8411 or by email at vpatluri@ieee.org, and Mr. Bruce J. Ladewig, Section Chair, at (480) 620-9291 or by email at bruceladewig@ieee.org.

IEEE Phoenix Section Student Scholarships

The IEEE Phoenix Section awards Student Scholarships to full-time graduate and undergraduate students who are IEEE student members. The applying student must attend a university in the Phoenix Section during 2014. The universities include Arizona State University, Arizona State University Polytechnic, DeVry University, Embry-Riddle Aeronautical University, and Northern Arizona University.

The student should submit a completely filled application along with financial aid statement; a one-page personal statement of achievements, interests, and goals; official transcripts of all college work; and recommendation letters. The scholarships are awarded based on academic achievement, financial need, and service to the IEEE.

Student scholarship winners, upon receiving notification from IEEE Phoenix Section Awards Committee, should send by email completely filled either Form W-9 for US Citizen or Form W-8 for Non-US Resident to Mr. Michael Deering, Director of Development, IEEE Foundation, at m.deering@ieee.org with a copy to Dr. Vasudeva P. Atluri, Section Award Committee Chair, at vpatluri@ieee.org by Friday, January 2nd, 2015.

The IEEE Phoenix Section will present the following Student Scholarship awards at the annual banquet scheduled for Saturday, February 7th, 2015 at Hilton Phoenix Airport located at 2435 South 47th Street, Phoenix, AZ – 85034 from 5:30 PM to 9:30 PM (Tel: 480-894-1600):

“Atluri Award” sponsored by Dr. Vasudeva Prasad Atluri and Dr. Satyavathi Atluri. Total of two award recipients are presented with a plaque and a check for $1000.00 each. Only graduate students are eligible for these awards.

“Al Gross Award” sponsored by IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society Phoenix Chapter. The award recipient is presented with a plaque and a check for $1000.00. Graduate and undergraduate students are eligible for this award.

“Irv Kaufman Award” sponsored by IEEE Waves and Devices Phoenix Chapter. The award recipient is presented with a plaque and a check for $1000.00. Graduate and undergraduate students are eligible for this award.

“Dieter Schroder Award” sponsored by IEEE Phoenix Section. The award recipient is presented with a plaque and a check for $1000.00. Graduate and undergraduate students are eligible for this award.

The checks for these four awards are given out from the IEEE Phoenix Section Student Scholarship Endowment administered by the IEEE Foundation. To learn more about IEEE Foundation, access http://www.ieeefoundation.org/.

Key dates:

Application submission deadline: Sunday, December 28th, 2014

Scholarship recipients will be informed on: Wednesday, December 31st, 2014

Phoenix Section LinkedIn Group

If you are interested in professional networking and shared Section related updates & discussions join the IEEE Phoenix Section Group on LinkedIn. Signing up only takes minutes and is free. A job board is available as well.

You can also go to IEEE Phoenix Section LinkdIn page by clicking in button on the IEEE Phoenix Section home page

IEEE Phoenix Section Ventures into Social Media

You can access the web page three ways:
Use the URL: https://www.facebook.com/IEEEPhoenixSection
Click on the Facebook logo f link from IEEE Phoenix section home page.
Search for IEEE Phoenix Section from your Facebook page.

We need following help.

1. Each of you access the IEEE Phoenix Section Web page and click on "Like" hyperlink.
2. Go on the Friends section of the page and "Invite Your Friends." Once your click on Invite button, it will get your email contact list. Your facebook contact list will already be populated with your Facebook friends and you can simply click the Invite button next to their name. Please invite as many friends as you can.
3. Provide me the contents for posting on a regular basis - meeting/ event announcements, Event pictures, Videos.
4. Start some discussion topics under - Status section.

IEEE Membership Grade Advancement

IEEE Phoenix Section Executive Committee encourages all to apply for advancement in membership grade to Senior Member and Fellow Grade. Please review the requirements at www.ieee.org. Please contact IEEE Phoenix Section Membership Development Chair, Dr. Vasudeva P. Atluri, at vpatluri@ieee.org for additional information.

Enhanced Senior Member Application Launched

Effective 29 July 2011, IEEE Admission and Advancement launched a new Senior Member Application. The new application includes numerous enhancements, based on feedback from volunteers and members, including:

- New user friendly format / design
- Secure environment (need IEEE Web account)
- Ability to save application in “draft” form
- Ability to upload resume or Curriculum Vitae (up to 3 MB)
- Applicant can view application online
- Applicant can view status of requested reference forms
- References will be notified by email to provide applicant reference
- References will have the ability to view their completed reference form(s)
- Real time application status

The goal is to provide prospective Senior Members with an easy to use and intuitive interface, while streamlining internal operations at the same time. View the new Senior Member application.

IEEE Member’s Benefits

IEEE-USA Offering Survivor Planning E-book Free to IEEE Members

December Free E-Book

IEEE-USA is once again offering a complimentary e-book to IEEE members. The December featured selection is “Starting Your Start-Up -- Book 2: Market Size and Strategy," by Tanya Candia.

The “Starting Your Start-Up” e-book series is designed for the engineer or entrepreneur who has a promising product or service idea, but no real marketing expertise. “Book 2: Market Size and Strategy” helps flesh out the initial plan and find the real market size, even when dealing with a disruptive technology in which market size data is hard to find. The book also helps the entrepreneur better understand the target buyer and how to communicate the value of their product or service, thus increasing the probability of early and ongoing sales.

Candia shares that “choosing a market cannot be done lightly, yet many startups ignore this step and rush to market with a product that they feel is suited to anyone.” Choosing the first market segment involves the following steps, among others: selecting the candidate industries/markets; segmenting the markets; defining characteristics of each segment; determining the optimal category; short-listing and sizing the segments; and selecting your target market and segment.

"Starting Your Start-Up -- Book 2: Market Size and Strategy" can be downloaded at http://www.ieeeusa.org/communications/ebooks/files/oct14/28vknso/Starting-Your-Start-Up-Book-2.pdf for free to IEEE members. It's $9.99 for non-members.

In January, IEEE-USA E-books will offer to members a complimentary copy of Gus Gaynor's "Shaping an Engineering Career -- Book 1: Responding to Career Challenges -- A Personal Journey."

Call for Authors

IEEE-USA E-books seek authors to write an e-book or e-book series on career guidance and development topics. If you have an idea that you think will benefit members in a particular area of expertise, please email your proposal to IEEE-USA Publishing Manager Georgia C. Stelluto at g.stelluto@ieee.org, and IEEE-USA Communications Committee Chair Gus Gaynor at g.gaynor@ieee.org.

IEEE-USA serves the public good and promotes the careers and public policy interests of more than 200,000 engineering, computing and technology professionals who are U.S. members of IEEE.

Web: www.ieeeusa.org
Facebook: www.facebook.com/ieeeusa
Twitter: www.twitter.com/ieeeusa
Join IEEE: www.ieee.org/join

Contact: Sharon C. Richardson, Coordinator
IEEE-USA Communications & Publishing
1 202 530 8363
s.richardson@ieee.org

GoogleApps@IEEE Now Available to IEEE Members

GoogleApps@IEEE is a suite of products offered to IEEE members to enhance peer-to-peer communications and collaboration. The suite of applications includes e-mail, calendaring, contacts, and document sharing along with other collaborative tools. 30G of available cloud storage memory is available for these applications. Learn more about http://www.ieee.org/googleapps

GoogleApps@IEEE is available to members at no additional cost, bringing access to:

- A unique IEEE e-mail address (e.g., John.A.Doe@ieee.org);
- Mail forwarding or e-mail inbox (Gmail);
- 30-gigabytes of shared storage (Gmail and Google Drive);
- 99.9 percent up time guaranteed by Google;
- Advertisement-free Gmail;
- Files stored in the cloud for easy sharing and access from anywhere via Google Drive.